

Assembly Bill of Materials

Texas Instruments

Project Name:	PMP9456
Project File:	PMP9456.PrpPcb
Base ID:	PMP9456
Schematic Rev:	E1
Generated:	4/23/2014 11:59:22 AM

Item	Designator	Description	Manufacturer	PartNumber	Quantity
1	!PCB	Printed Circuit Board	Any	PMP9456	1
2	C01, C02	CAP, CERM, 0.022uF, 100V, +/-5%, X7R, 0805	AVX	08051C223JAT2A	2
3	C04	CAP, AL, 470uF, 16V, +/-20%, 0.17 ohm, SMD	Nichicon	UUD1C471MNL1GS	1
4	CBIAS	CAP, CERM, 4.7uF, 50V, +/-10%, X7R, 1206	MuRata	GRM31CR71H475KA12L	1
5	CBOOT	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0805	AVX	08053C104KAT2A	1
6	CIN1, CIN2	CAP, CERM, 4.7uF, 50V, +/-10%, X7R, 1210	MuRata	GRM32ER71H475KA88L	2
7	CIN3	CAP, AL, 100uF, 63V, +/-20%, 0.35 ohm, SMD	Panasonic	EEE-FK1J101P	1
8	CIN4	CAP, CERM, 0.47uF, 100V, +/-10%, X7R, 0805	MuRata	GRM21BR72A474KA73L	1
9	CO3	CAP, CERM, 1uF, 25V, +/-10%, X5R, 0805	AVX	08053D105KAT2A	1
10	CVCC	CAP, CERM, 10uF, 10V, +/-20%, X5R, 1206	TDK	C3216X5R1A106M	1
11	D1	Diode, Zener, 6.8V, 500mW, SOD-123	ON Semiconductor	MMSZ4692T1G	1
12	DSWL	Diode, Schottky, 70V, 1A, SMA	Diodes Inc.	B170-13-F	1
13	J1, J2	Terminal Block, 2x1, 7.62mm, TH	Phoenix Contact	1732720	2
14	L1	Inductor, Shielded Drum Core, Ferrite, 68uH, 2.1A, 0.14 ohm, SMD	Sumida	CDRH127NP-680MC	1
15	R1	RES, 499 ohm, 1%, 0.125W, 0805	Vishay-Dale	CRCW0805499RFKEA	1
16	R2, R3	RES, 6.65 ohm, 1%, 0.25W, 1206	Yageo America	RC1206FR-076R65L	2
17	R6	RES, 80.6k ohm, 1%, 0.125W, 0805	Panasonic	ERJ-6ENF8062V	1
18	RENB	RES, 221k ohm, 1%, 0.125W, 0805	Vishay-Dale	CRCW0805221KFKEA	1
19	RENT	RES, 768k ohm, 1%, 0.125W, 0805	Panasonic	ERJ-6ENF7683V	1
20	RPGI	RES, 100k ohm, 1%, 0.125W, 0805	Vishay-Dale	CRCW0805100KFKEA	1
21	TP3, TP5, TP10, TP17	Test Point, TH, Multipurpose, White	Keystone	5012	4
22	U1	6th Gen Buck Regulator	Texas Instruments	LM46001	1

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